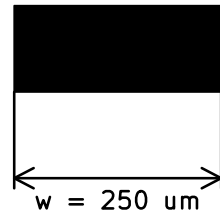
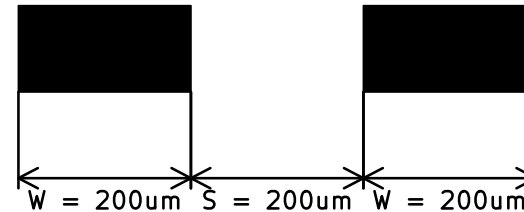


Top Layer
50 Ohm microstrip



Top Layer
90 Ohm differential microstrip



Top Paste

Top Soldermask

1 – Top Copper (35 um Final)

Prepreg 2x ISOLA IS400 (125 um Final)

2 – Inner Copper (35 um)

Core (1200 um)

3 – Inner Copper (35 um)

Prepreg 2x ISOLA IS400 (125 um Final)

4 – Bottom Copper (35 um Final)

Bottom Soldermask

Total thickness: 1.6 mm

